ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
upplier Inform	ation														
Company name*			Company unique ID			J	Unique ID Authority					Response Date*			
nsemi											2023-06-08				
Contact Name		Title - Contact			I	Phone - Contact*					Email - Contact*				
Product-Env-Stewar	rds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Envi	roduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester	r Item Number	Mfr Item Number		Mfr Item Name			Effective Date Version		Manufacturing Site		V	Veight*	UOM	Unit Type	
		E7111-0-	102A19-AG	EZAIRO 7111, T&	kR MPQ 250		2023-06-08			CA1		4	9.22926	mg	Each
Ianufacturing I	Proccess Information	on						•							
Terminal Plating / Grid Array Material Term			erminal Base	Alloy J-	STD-020 MS	SL Rating	Peak Pro	cess Bo	ly Temperature Max Time at Peak Temperature Number of Reflow Cycles				eles		
SnAgCu		C	U Alloy	3			260		C	30		second	ls 3		
omments															
TTENTION: MSL	3 Rated item requires I	Bake and Di	ry Pack (after	electrical test)											
or more informatio	on regarding material co	mposition p	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Capacitor	3.39	mg	Supplier	Silicon Dioxide	7631-86-9		0.062	mg
			Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.6855	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		0.0155	mg
			Supplier	Tin (Sn)	7440-31-5		0.1915	mg
			Supplier	Misc.	Proprietary Data		0.2285	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		1.3711	mg
			В	Nickel (Ni)	7440-02-0		0.1381	mg
			Supplier	Copper (Cu)	7440-50-8		0.6978	mg
Die	10.50806	mg	Supplier	Silicon (Si)	7440-21-3		10.5081	mg
Laminate Board	15.05	mg	Supplier	triethylenediamine	280-57-9		0.0005	mg
			Supplier	Sodium citrate	68-04-2		0.0003	mg
			Supplier	Tetraammine palladium (II) dichloride	13815-17-3		0.0006	mg
			Supplier	D.I. Water	7732-18-5		0.0603	mg
			Supplier	Nickel Sulfamate	13770-89-3		0.1004	mg
			Supplier	copper	7440-66-6		5.2118	mg
			Supplier	copper foil	N/A		0.5659	mg
			Supplier	continuous filament fiber glass	N/A		1.7666	mg
			Supplier	Defoamers	N/A		0.078	mg
			Supplier	Phthalocyanine blue	N/A		0.0111	mg
			Supplier	Organic Filler	N/A		0.0134	mg
			Supplier	Acrylate resin	N/A		0.7846	mg
			Supplier	Diproplyeneglycolmonomethylether	34590-97-8		0.1672	mg
			Supplier	Gold Potassium Cyanide	13967-50-5		0.0067	mg
			Supplier	Thermosetting resin	Proprietary Data		3.7992	mg
			Supplier	Silica	Proprietary Data		0.0156	mg
			Supplier	Talc	14807-96-6		0.0468	mg
			Supplier	3-methoxy-3-methylbutylacetate	103429-90-9		0.3455	mg
			Supplier	Naphthalene	91-20-3		0.0156	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		0.297	mg
			Supplier	Photoinitiator	Proprietary Data		0.0802	mg
			Supplier	Palladium (Pd)	7440-05-3		0	mg
			В	Nickel (Ni)	7440-02-0		0	mg

			Supplier	Gold (Au)	7440-57-5	0	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	0.0802	mg
			Supplier	Copper (Cu)	7440-50-8	1.0117	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	0.5907	mg
Mold Compound-Black	16.5	mg		Epoxy resin	proprietary data	1.32	mg
			Supplier	Phenol Resin	Proprietary Data	0.825	mg
			Supplier	Metal Hydroxide	Proprietary Data	0.165	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9	4.125	mg
			Supplier	Carbon Black (C)	1333-86-4	0.165	mg
			Supplier	Fused Silica (SiO2)	60676-86-0	9.9	mg
Solder Paste	3.12	mg	Supplier	2-(2-Hexyloxyethoxy) ethanol	112-59-4	0.1248	mg
			Supplier	Denatured Acid Hydrogenation Rosin	Proprietary	0.1248	mg
			Supplier	Dimer Acid	Proprietary	0.0624	mg
			Supplier	Silver (Ag)	7440-22-4	0.0936	mg
			Supplier	Tin (Sn)	7440-31-5	2.6832	mg
			Supplier	Copper (Cu)	7440-50-8	0.0312	mg
Wire Bond - Au	0.6612	mg	Supplier	Gold (Au)	7440-57-5	0.6612	mg